

# SEMiX503GD126HDc



SEMiX® 33c

## Trench IGBT Modules

### SEMiX503GD126HDc

#### Features

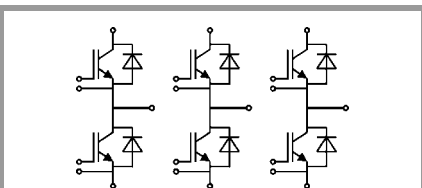
- Homogeneous Si
- Trench = Trenchgate technology
- $V_{CE(sat)}$  with positive temperature coefficient
- High short circuit capability
- UL recognised file no. E63532

#### Typical Applications\*

- AC inverter drives
- UPS
- Electronic Welding

#### Remarks

- Case temperatur limited to  $T_C=125^\circ\text{C}$  max.
- Not for new design



GD

Absolute Maximum Ratings				
Symbol	Conditions	Values	Unit	
<b>IGBT</b>				
$V_{CES}$		1200	V	
$I_C$	$T_j = 150^\circ\text{C}$	$T_c = 25^\circ\text{C}$	466	A
		$T_c = 80^\circ\text{C}$	327	A
$I_{Cnom}$		300	A	
$I_{CRM}$	$I_{CRM} = 2 \times I_{Cnom}$	600	A	
$V_{GES}$		-20 ... 20	V	
$t_{psc}$	$V_{CC} = 600\text{ V}$ $V_{GE} \leq 20\text{ V}$ $V_{CES} \leq 1200\text{ V}$	$T_j = 125^\circ\text{C}$	10	$\mu\text{s}$
$T_j$		-40 ... 150	$^\circ\text{C}$	
<b>Inverse diode</b>				
$I_F$	$T_j = 150^\circ\text{C}$	$T_c = 25^\circ\text{C}$	412	A
		$T_c = 80^\circ\text{C}$	284	A
$I_{Fnom}$		300	A	
$I_{FRM}$	$I_{FRM} = 2 \times I_{Fnom}$	600	A	
$I_{FSM}$	$t_p = 10\text{ ms, sin } 180^\circ, T_j = 25^\circ\text{C}$	2000	A	
$T_j$		-40 ... 150	$^\circ\text{C}$	
<b>Module</b>				
$I_{t(RMS)}$		600	A	
$T_{stg}$		-40 ... 125	$^\circ\text{C}$	
$V_{isol}$	AC sinus 50Hz, $t = 1\text{ min}$	4000	V	

Characteristics					
Symbol	Conditions	min.	typ.	max.	Unit
<b>IGBT</b>					
$V_{CE(sat)}$	$I_C = 300\text{ A}$ $V_{GE} = 15\text{ V}$ chipelevel	$T_j = 25^\circ\text{C}$	1.7	2.1	V
		$T_j = 125^\circ\text{C}$	2	2.45	V
$V_{CE0}$		$T_j = 25^\circ\text{C}$	1	1.2	V
		$T_j = 125^\circ\text{C}$	0.9	1.1	V
$r_{CE}$	$V_{GE} = 15\text{ V}$	$T_j = 25^\circ\text{C}$	2.3	3.0	$\text{m}\Omega$
		$T_j = 125^\circ\text{C}$	3.7	4.5	$\text{m}\Omega$
$V_{GE(th)}$	$V_{GE}=V_{CE}, I_C = 12\text{ mA}$	5	5.8	6.5	V
$I_{CES}$	$V_{GE} = 0\text{ V}$ $V_{CE} = 1200\text{ V}$	$T_j = 25^\circ\text{C}$	0.1	0.3	mA
		$T_j = 125^\circ\text{C}$			mA
$C_{ies}$	$V_{CE} = 25\text{ V}$ $V_{GE} = 0\text{ V}$	$f = 1\text{ MHz}$	21.6		nF
$C_{oes}$		$f = 1\text{ MHz}$	1.13		nF
$C_{res}$		$f = 1\text{ MHz}$	0.98		nF
$Q_G$	$V_{GE} = -8\text{ V...} + 15\text{ V}$		2400		nC
$R_{Gint}$	$T_j = 25^\circ\text{C}$		2.50		$\Omega$
$t_{d(on)}$	$V_{CC} = 600\text{ V}$ $I_C = 300\text{ A}$	$T_j = 125^\circ\text{C}$	275		ns
$t_r$		$T_j = 125^\circ\text{C}$	55		ns
$E_{on}$	$R_{G on} = 2.2\ \Omega$	$T_j = 125^\circ\text{C}$	28		mJ
$t_{d(off)}$	$R_{G off} = 2.2\ \Omega$	$T_j = 125^\circ\text{C}$	625		ns
$t_f$		$T_j = 125^\circ\text{C}$	125		ns
$E_{off}$		$T_j = 125^\circ\text{C}$	44		mJ
$R_{th(j-c)}$	per IGBT			0.08	K/W

# SEMiX503GD126HDc



SEMiX® 33c

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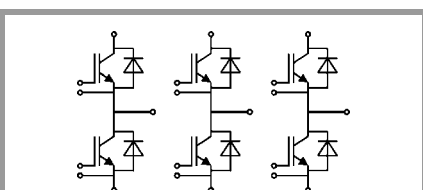
#### Typical Applications\*

- AC inverter drives
- UPS
- Electronic Welding

#### Remarks

- Case temperatur limited to  $T_C=125^\circ\text{C}$  max.
- Not for new design

Characteristics						
Symbol	Conditions		min.	typ.	max.	Unit
<b>Inverse diode</b>						
$V_F = V_{EC}$	$I_F = 300\text{ A}$ $V_{GE} = 0\text{ V}$ chip	$T_j = 25^\circ\text{C}$		1.6	1.80	V
		$T_j = 125^\circ\text{C}$		1.6	1.8	V
$V_{F0}$		$T_j = 25^\circ\text{C}$	0.9	1	1.1	V
		$T_j = 125^\circ\text{C}$	0.7	0.8	0.9	V
$r_F$		$T_j = 25^\circ\text{C}$	1.7	2.0	2.3	m $\Omega$
		$T_j = 125^\circ\text{C}$	2.3	2.7	3.0	m $\Omega$
$I_{RRM}$	$I_F = 300\text{ A}$	$T_j = 125^\circ\text{C}$		400		A
$Q_{rr}$	$di/dt_{off} = 6900\text{ A}/\mu\text{s}$	$T_j = 125^\circ\text{C}$		77		$\mu\text{C}$
$E_{rr}$	$V_{GE} = -15\text{ V}$ $V_{CC} = 600\text{ V}$	$T_j = 125^\circ\text{C}$		32.5		mJ
$R_{th(j-c)}$	per diode				0.14	K/W
<b>Module</b>						
$L_{CE}$				20		nH
$R_{CC'+EE'}$	res., terminal-chip	$T_C = 25^\circ\text{C}$		0.7		m $\Omega$
		$T_C = 125^\circ\text{C}$		1		m $\Omega$
$R_{th(c-s)}$	per module			0.014		K/W
$M_s$	to heat sink (M5)		3		5	Nm
$M_t$		to terminals (M6)	2.5		5	Nm
						Nm
$w$					900	g
<b>Temperatur Sensor</b>						
$R_{100}$	$T_C=100^\circ\text{C}$ ( $R_{25}=5\text{ k}\Omega$ )			$493 \pm 5\%$		$\Omega$
$B_{100/125}$	$R_{(T)}=R_{100}\exp[B_{100/125}(1/T-1/T_{100})]$ ; $T[\text{K}]$ ;			$3550$ $\pm 2\%$		K



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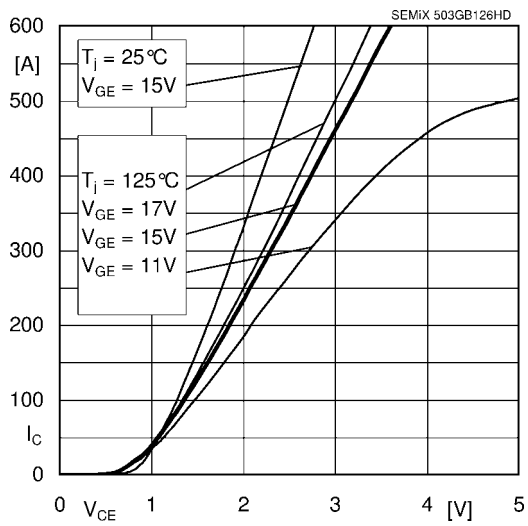


Fig. 1: Typ. output characteristic, inclusive  $R_{CC'+EE'}$

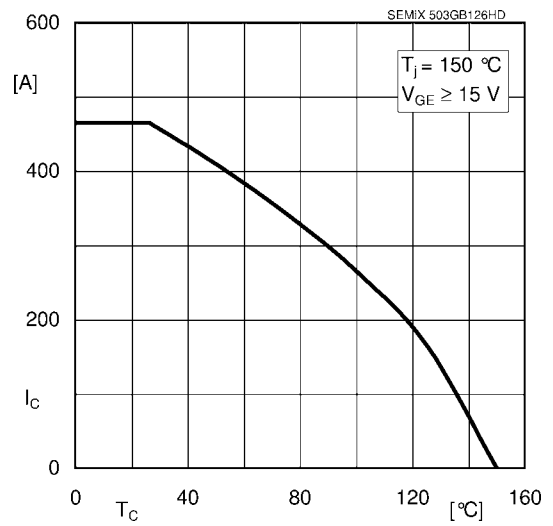


Fig. 2: Rated current vs. temperature  $I_c = f(T_c)$

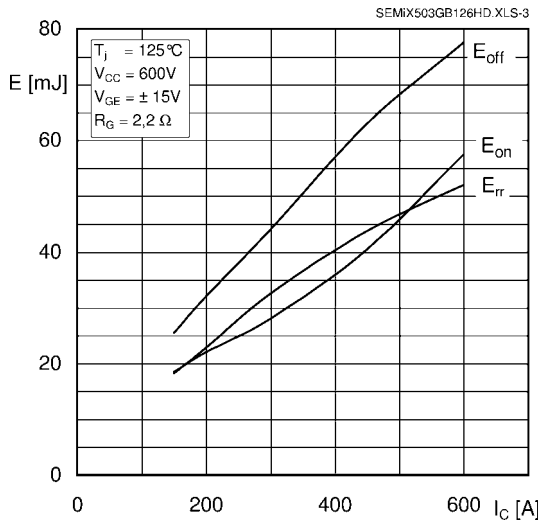


Fig. 3: Typ. turn-on /-off energy =  $f(I_c)$

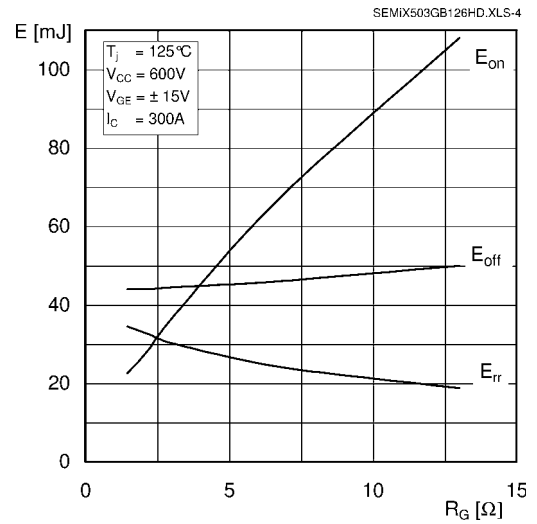


Fig. 4: Typ. turn-on /-off energy =  $f(R_G)$

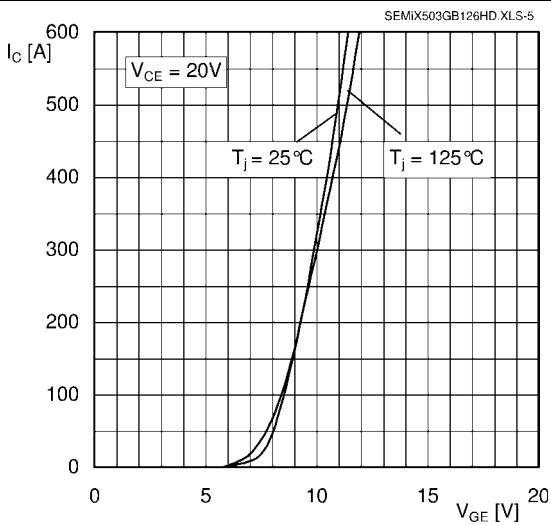


Fig. 5: Typ. transfer characteristic

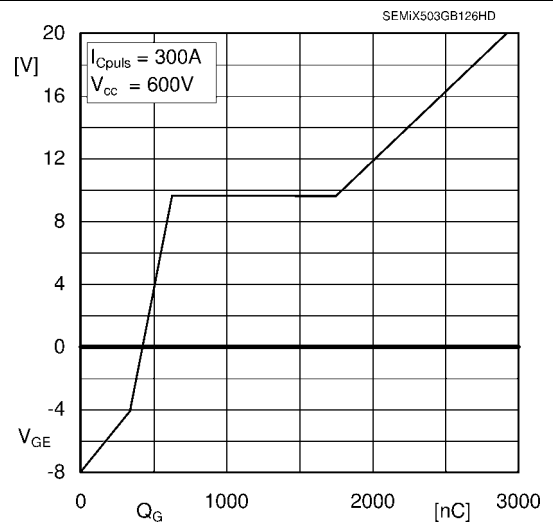


Fig. 6: Typ. gate charge characteristic

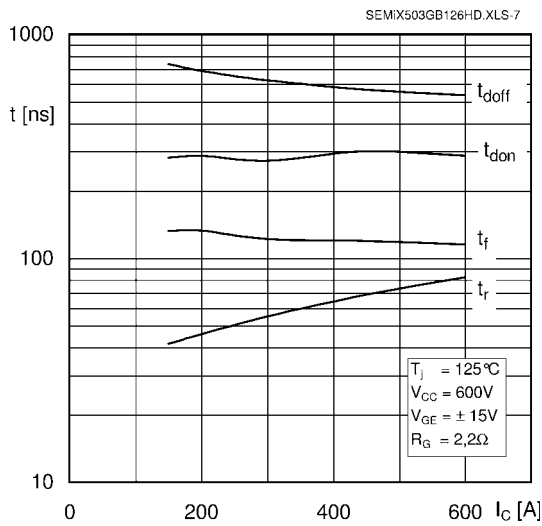


Fig. 7: Typ. switching times vs.  $I_C$

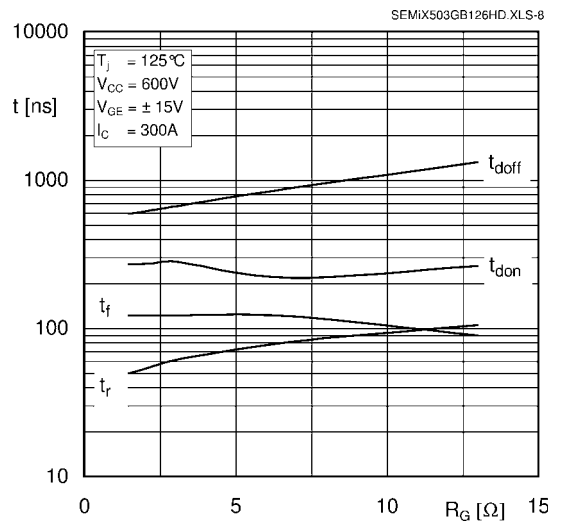


Fig. 8: Typ. switching times vs. gate resistor  $R_G$

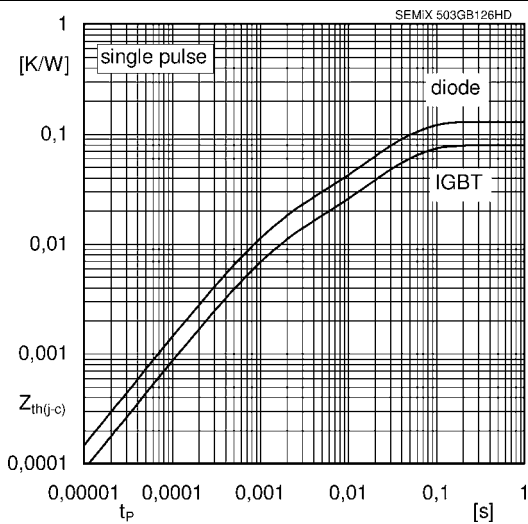


Fig. 9: Typ. transient thermal impedance

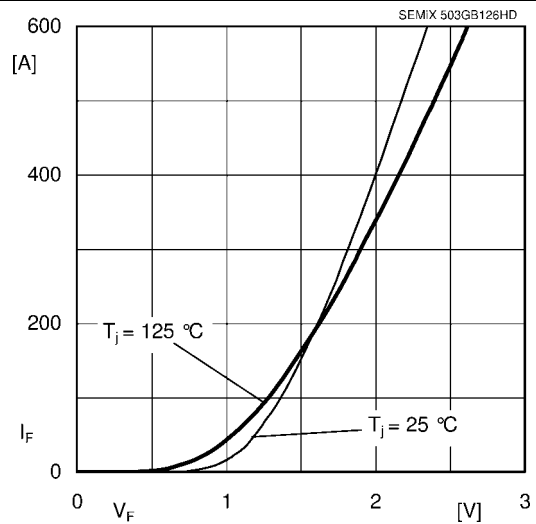


Fig. 10: Typ. CAL diode forward charact., incl.  $R_{CC+EE}$

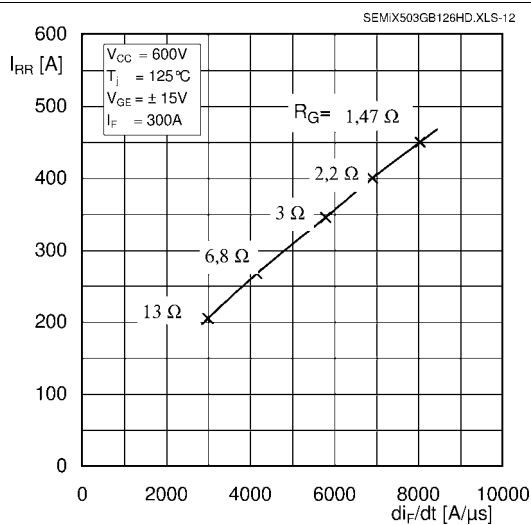


Fig. 11: Typ. CAL diode peak reverse recovery current

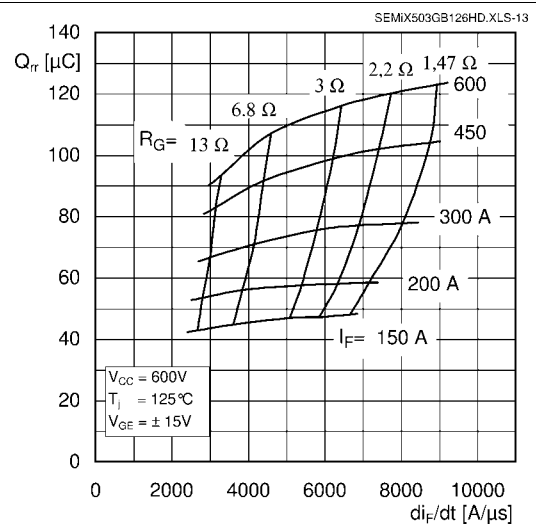
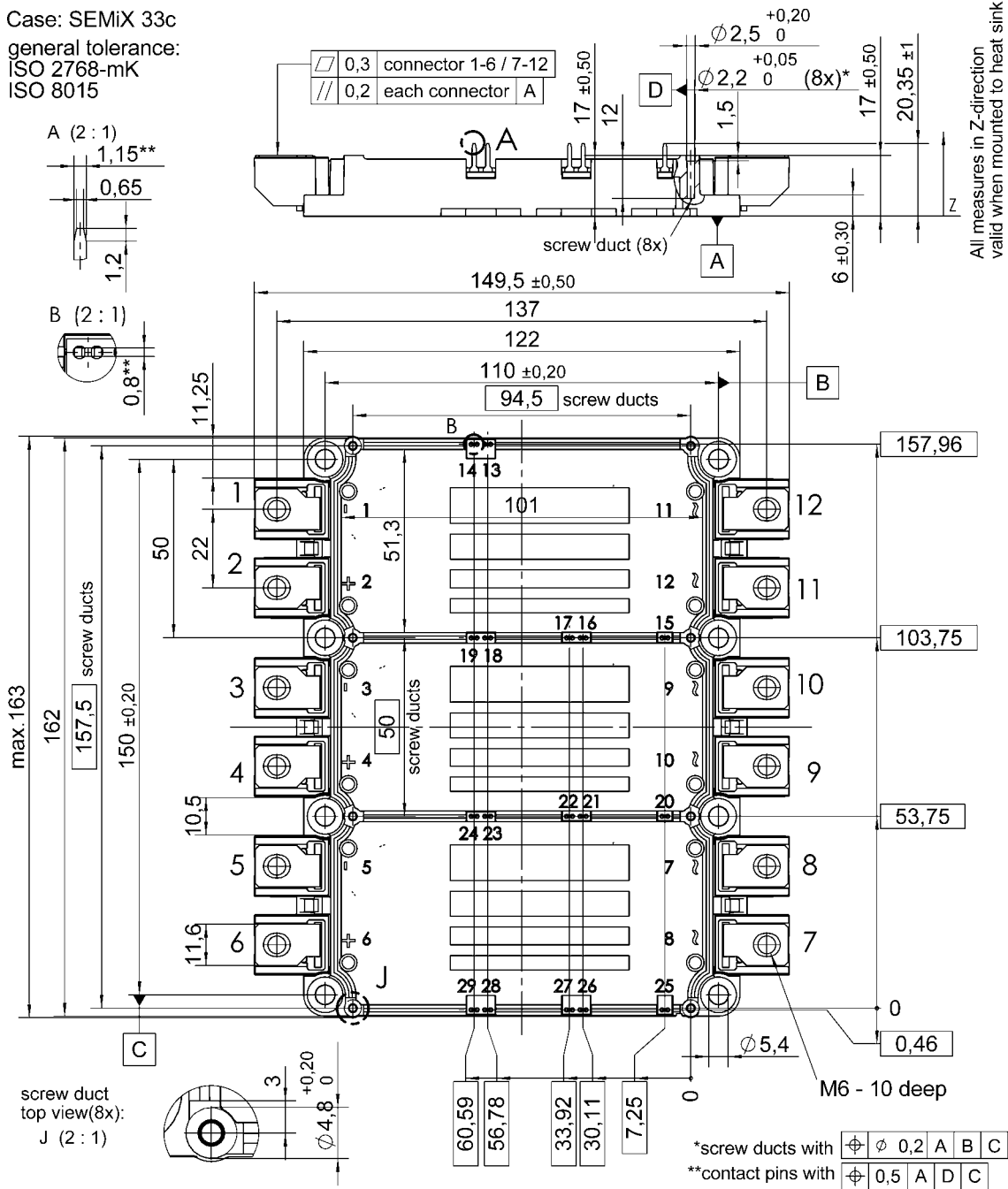


Fig. 12: Typ. CAL diode recovery charge

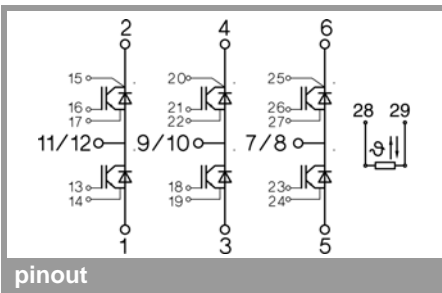
# SEMiX503GD126HDc

Case: SEMiX 33c  
 general tolerance:  
 ISO 2768-mk  
 ISO 8015



All measures in Z-direction  
 valid when mounted to heat sink

SEMiX 33c



This is an electrostatic discharge sensitive device (ESDS), international standard IEC 60747-1, Chapter IX

\* The specifications of our components may not be considered as an assurance of component characteristics. Components have to be tested for the respective application. Adjustments may be necessary. The use of SEMIKRON products in life support appliances and systems is subject to prior specification and written approval by SEMIKRON. We therefore strongly recommend prior consultation of our personal.